925294814



PATENT

Docket No.: P6D2-US

REMARKS

Claim 37 has been amended, and claim 43 has been newly added. Claims 37-43 are pending in the application. Applicant respectfully requests reexamination and reconsideration of the application in light of the amendments and the following remarks.

Claims 37-42 have been rejected based on statutory-type double patenting in view of US Patent 5,864,946. Applicants have amended claim 37, replacing "silicon wafer" with the broader term "substrate." Claim 37 now is different in scope (i.e., it broader) than claim 1 of the '946 patent. Claim 37 of the instant application and claim 1 of the '946 patent are not drawn to identical subject matter. Accordingly, the statutory-double patenting rejection should be with drawn.

Claims 37-42 have also been rejected based on obvious-type double patenting in view of US Patent 5,864,946. Applicants submit wherewith a terminal disclaimer, which Applicants believe overcomes this obvious-type double patenting rejection.

In view of the foregoing, Applicants respectfully submit that the application is in condition for allowance. If the Examiner believes that a discussion with Applicants' attorney would be helpful, the Examiner is invited to contact the undersigned at (925) 456-3915.

Although Applicant believes that all necessary extensions of time have been requested and fees have been authorized in papers filed herewith, Applicants hereby petition the Commissioner for any extension of time deemed necessary for acceptance of this paper, and Applicants authorize the Commissioner to charge any fee due in connection with the filing of this paper to Deposit Account No. 50-0285 (order no. P6D2-US).

Respectfully submitted.

Date: February 25, 2002

N. Kenneth Burraston Registration No. 39,923

FormFactor, Inc. Legal Department 2140 Research Dr. Livermore, CA 94550 925-294-4300 925-294-8147 Fax



PATENT Docket No.: P6D2-US

Version With Markings To Show Changes Made

37. (Amended) Method of fabricating tip structures for ends of contact structures, comprising:

depositing at least one layer of at least one conductive material on a surface of a [silicon wafer] substrate;

depositing a layer of masking material atop the at least one conductive layer; patterning openings in the masking material; depositing at least one layer of at least one conductive material into the openings; and removing the masking material.



PATENT P6D2-US

CERTIFICATE OF MAILING BY "FIRST CLASS MAIL" 37 C.F.R. §1.8

I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail on February 25, 2002 _ in an envelops addressed to: Assistant Commissioner for Patents, Washington, D.C. 20231.

and Cont Patti Crowder

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In the application of: Eldridge et al.

Application No.: 09/846,490

Filing Date: April 30, 2001

For: PROBE CARD ASSEMBLY AND KIT, AND METHODS OF USING SAME

Examiner: C. Arbes

Group Art Unit: 3729

NOTICE OF RELATED PATENTS AND APPLICATIONS

Assistant Commissioner for Patents

Washington, D.C. 20231

Sir:

Applicants wish to draw the Examiner's attention to the following commonly owned applications and patents (and the art cited therein), whose subject matter may be deemed related to the subject matter of the above-identified application.

US pat. appl. serial no.:	09/295,269	(P2D7-US)	filed	April 20, 1999
US pat. appl. serial no.:	10/011,335	(P6C1-US)	filed	December 5, 2001
US pat. appl. serial no.:	10/034,543	(P6C2-US)	filed	December 27, 2001
US pat. appl. serial no.:	10/034,528	(P6C3-US)	filed	December 27, 2001
US pat. appl. serial no.:	09/953,666	(P17D1-US)	filed	September 14, 2001
US pat. appl. serial no.:	09/023,859	(P47-US)	filed	February 13, 1998

US pat. no.:	6,336,269	(P3-US)	issued	January 8, 2002
US pat. no.:	5,974,662	(P6-US)	issued	November 2, 1999
US pat. no.:	6,246,247	(P6D1-US)	issued	June 12, 2001
US pat. no.:	5,864,946	(P7D6-US)	issued	February 2, 1999

Respectfully submitted,

Date: February 25, 2002

N. Kenneth Burraston Reg. No. 39,923

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Telephone: (925) 294-4300

Application No.: 09/846,490 Attorney	Docket No.: P6D2-US			
Inventor: Benjamin N. Eldridge et al. Date Du	Due: February 25, 2002			
Title: PROBE CARD ASSEMBLY AND KIT, AND METHO	DDS OF USING SAME			
Receipt is hereby acknowledged of the following:				
Patent Application (No. pgs) Information Disclosure Statement wPTO 1449 Drawings Sheets Declaration and Power of Attorney (Copy from prior Appl.) Assignment w/Cover Sheet Check No., In the amount of \$ Revocation/Power of Attorney & Change of Corres. Address Certification under 3.73 Tempinal Disclaimer Transmittal Notice Of Related Patents & Applications	☐ Petition for Extension of Time ☐ Reep. to Notice to File Missing Parts ☐ Response/Amendment ☐ Issue Fee Transmittel ☐ Submission of Formal Drawings ☐ Notice of Appeal ☐ Appeal Brief ☐ Application Data Sheet ☐ Certificate of Mailing ☑ Express Mail Certificate			
Express Mail label No.:	Date Meiled: February 25, 2002			

Application No.; 09/846,490	Attorney Docket No.: P6D2-US
Inventor. Benjamin N. Eldridge et al.	Date Due: February 25, 2002
Title: PROBE CARD ASSEMBLY AND KIT, AN	DANETHOUS OF USING SAME
/	4
Receipt is hereby acknowledged of the following:	MAR 0 8 7502
Patent Application (No. pgs) Information Disclosure Statement wpro 1449 Drawings Sheets Declaration and Power of Attorney (Copy from prid Assignment w/Cover Sheet Check No., in the amount of \$ Revocation/Power of Attorney & Change of Corres Certification under 3.73 Terminal Disclaimer Transmittal Notice Of Related Patents & Applications	Submission of Formal Drawings Notice of Anneal
Express Mail label No.:	Date Mailed: February 25, 2002

